

## High Output Current, Rail-to-Rail Input/Output Dual CMOS Operational Amplifier

### ■ GENERAL DESCRIPTION

The **NJU77902** is a Rail-to-Rail input and output dual CMOS operational amplifier that features high output current drive.

This device is stable to capacitive load and can charge and discharge capacitance quickly by high output current up to 1000mA. In addition, it is ideal for buffer amplifiers as the output stage can supply a respectable amount of current with minimal headroom from either rail.

### ■ PACKAGE OUTLINE



**NJU77902KW2**  
(ESON8-W2)

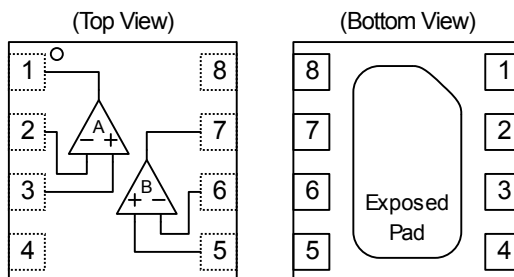
### ■ FEATURES

- Output Peak Current      1000mA (typ.)
- Rail-to-Rail Input/Output
- Wide Operating Voltage    6V to 18V
- Slew Rate                    9V/μs (typ.)
- Package                      ESON8-W2 (3.0mm x 3.0mm)
- Enhanced RF Noise Immunity
- CMOS Process

### ■ APPLICATION

- TFT-LCD panel  $V_{COM}$  driver
- Instrument Control Voltage Source

### ■ PIN CONFIGURATION



**NJU77902KW2**

### PIN FUNCTION

1. A OUTPUT
2. A -INPUT
3. A +INPUT
4.  $V_{SS}$
5. B +INPUT
6. B -INPUT
7. B OUTPUT
8.  $V_{DD}$

About Exposed Pad

Connect the Exposed Pad on the  $V_{SS}$ .

## ■ ABSOLUTE MAXIMUM RATINGS (Ta=25°C, unless otherwise noted.)

PARAMETER	SYMBOL	RATINGS	UNIT
Supply Voltage	V <sub>DD</sub>	+20	V
Power Dissipation	P <sub>D</sub>	560(Note1), 750(Note2), 910(Note3), 2500(Note4)	mW
Output Peak Current	I <sub>OP</sub>	1000	mA
Input Common Mode Voltage	V <sub>ICM</sub>	V <sub>SS</sub> -0.3 to V <sub>DD</sub> +0.3	V
Differential Input Voltage	V <sub>ID</sub>	18 (Note5)	V
Operating Temperature Range	T <sub>opr</sub>	-40 to +85	°C
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C

(Note1) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4)

(Note2) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 2Layers FR-4, with Exposed Pad)

(Note3) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 4Layers FR-4)

(Note4) Mounted on glass epoxy board. (101.5×114.5×1.6mm: based on EIA/JEDEC standard, 4Layers FR-4, with Exposed Pad)

(For 4Layers: Applying 99.5×99.5mm inner Cu area and a thermal via hole to a board based on JEDEC standard JESD51-5)

(Note5) For supply voltage less than 18V, the absolute maximum rating is equal to the supply voltage.

## ■ RECOMMENDED OPERATING CONDITION (Ta=25°C)

PARAMETER	SYMBOL	RATING	UNIT
Supply Voltage	V <sub>DD</sub>	6.0 to 18.0	V

## ■ ELECTRICAL CHARACTERISTICS

(V<sub>DD</sub>=15V, V<sub>SS</sub>=0V, V<sub>IC</sub>=7.5V, R<sub>L</sub>=10kΩ to V<sub>DD</sub>/2, Ta=25°C, unless otherwise noted.)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
<b>• DC CHARACTERISTICS</b>						
Maximum Output Voltage	V <sub>OH1</sub>	R <sub>L</sub> = 10kΩ	14.8	14.9	-	V
	V <sub>OH2</sub>	I <sub>source</sub> = 200mA	14.2	14.5	-	V
	V <sub>OL1</sub>	R <sub>L</sub> = 10kΩ	-	0.1	0.2	V
	V <sub>OL2</sub>	I <sub>sink</sub> = 200mA	-	0.5	0.8	V
Input Offset Voltage	V <sub>IO</sub>	R <sub>S</sub> = 50Ω	-	1	10	mV
Input Bias Current	I <sub>B</sub>		-	1	-	pA
Input Offset Current	I <sub>IO</sub>		-	1	-	pA
Large Signal Voltage Gain	A <sub>V</sub>	V <sub>O</sub> = 13V/2V, R <sub>L</sub> =10kΩ	65	90	-	dB
Common Mode Rejection Ratio	CMR	V <sub>IC</sub> = 0V → 7.5V V <sub>IC</sub> = 7.5V → 15V	50	75	-	dB
Supply Voltage Rejection Ratio	SVR	V <sub>DD</sub> = 6V → 18V	60	75	-	dB
Input Common Mode Voltage Range	V <sub>ICM</sub>	CMR ≥ 50dB	0	-	15	V
Operating Current	I <sub>DD</sub>	No Signal, R <sub>L</sub> = open	-	7.0	9.0	mA
<b>• AC CHARACTERISTICS</b>						
Unity Gain Frequency	f <sub>t</sub>	C <sub>L</sub> = 10pF	-	3	-	MHz
Phase Margin	Φ <sub>M</sub>	C <sub>L</sub> = 10pF	-	50	-	deg
Equivalent Input Noise Voltage	V <sub>NI</sub>	f = 1kHz, R <sub>S</sub> = 100Ω	-	80	-	nV/√Hz
Total Harmonic Distortion+Noise	THD+N	G <sub>V</sub> = 6dB, C <sub>L</sub> = 10pF, f <sub>in</sub> = 1kHz, P <sub>O</sub> = 0.1W	-	0.02	-	%
Output Power	P <sub>O</sub>	f <sub>in</sub> =1kHz, C <sub>L</sub> =10pF, THD≤5%	-	3	-	mW
Channel Separation	CS	f = 1kHz	-	120	-	dB
<b>• TRANSIENT CHARACTERISTICS</b>						
Output Peak Current	I <sub>OP</sub>	(Note6)	-	1000	-	mA
Slew Rate	SR	G <sub>V</sub> = 0dB, C <sub>L</sub> = 10pF, V <sub>in</sub> = 4Vpp, (Note7)	5	9	-	V/μs

(Note6) Output peak current is defined by the lower value of the output source current or output sink current.

(Note7) Slew rate is defined by the lower value of the rise or fall.

## ■ Application Notes

### •Package Power, Power Dissipation and Output Power

IC is heated by own operation and possibly gets damage when the junction power exceeds the acceptable value called Power Dissipation  $P_D$ . The dependence of the NJU77902  $P_D$  on ambient temperature is shown in Fig 1. The plots are depended on following two points. The first is  $P_D$  on ambient temperature 25 °C, which is the maximum power dissipation. And the second is 0W, which means that the IC cannot radiate any more. The second point derives from the relation that maximum junction temperature  $T_{Jmax}$  is the same as storage temperature  $T_{stg}$ . Fig.1 is drawn by connecting those points and by the definition that the  $P_D$  lower than 25 °C is constant. Therefore, the  $P_D$  is shown following formula as a function of the ambient temperature between those points.

$$\text{Dissipation Power } P_D = \frac{T_{j \max} - T_a}{\theta_{ja}} \text{ [W]} \quad (T_a = 25 \text{ }^\circ\text{C to } T_a = 150 \text{ }^\circ\text{C})$$

Where,  $\theta_{ja}$  is heat thermal resistance which depends on parameters such as package material, frame material and so on. Therefore,  $P_D$  is different in each package.

While, the actual measurement of dissipation power on NJU77902 is obtained using following equation.

$$(\text{Actual Dissipation Power}) = (\text{Supply Voltage } V_{DD}) \times (\text{Supply Current } I_{DD}) - (\text{Output Power } P_o)$$

The NJU77902 should be operated in lower than  $P_D$  of the actual dissipation power.

To sustain the steady state operation, take account of the Dissipation Power and thermal design.

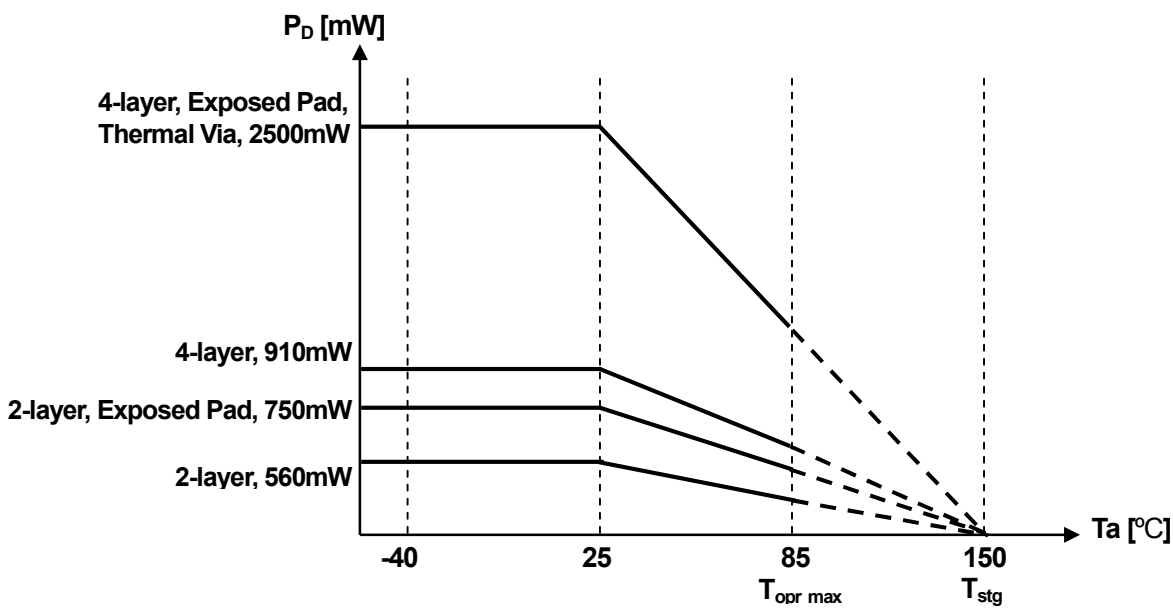
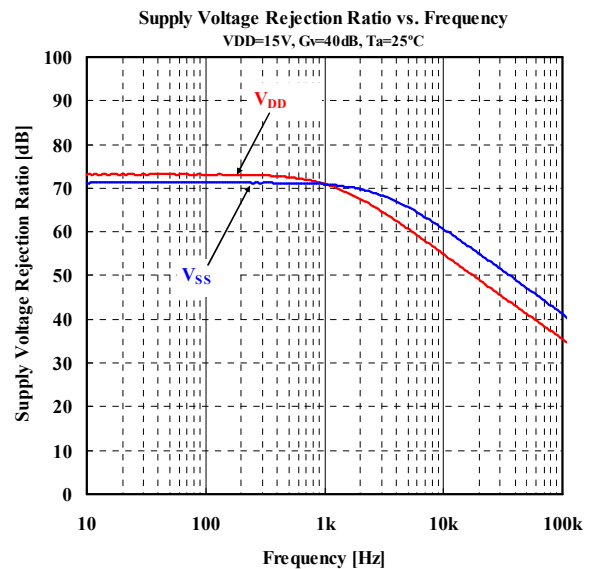
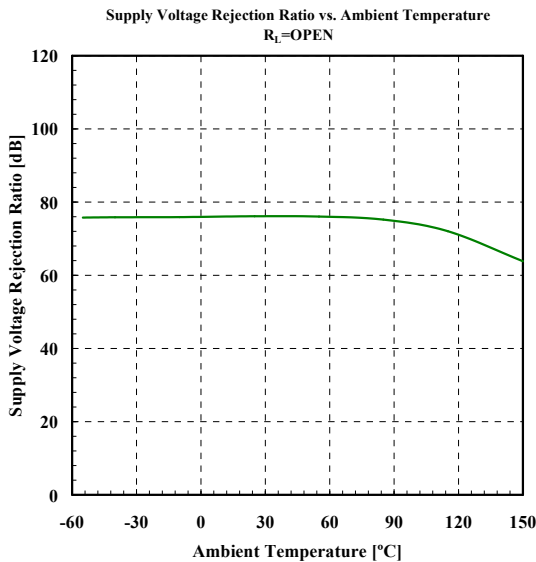
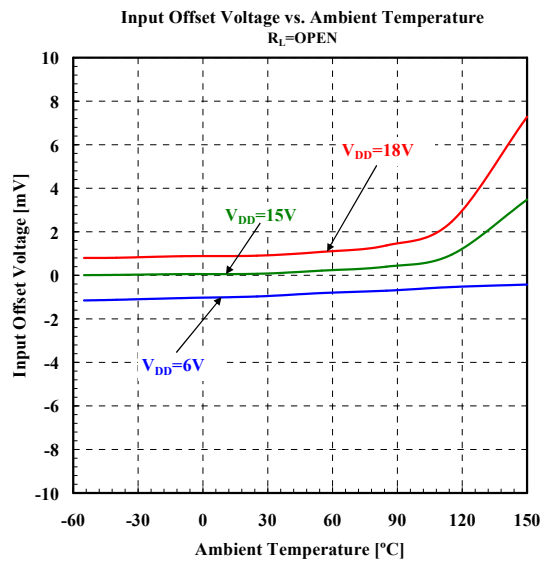
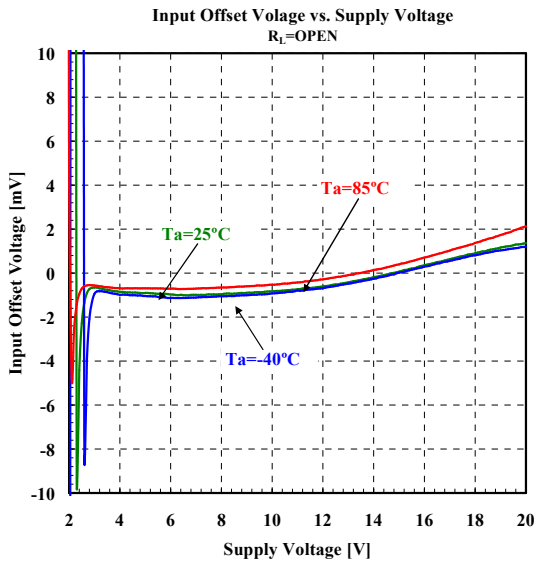
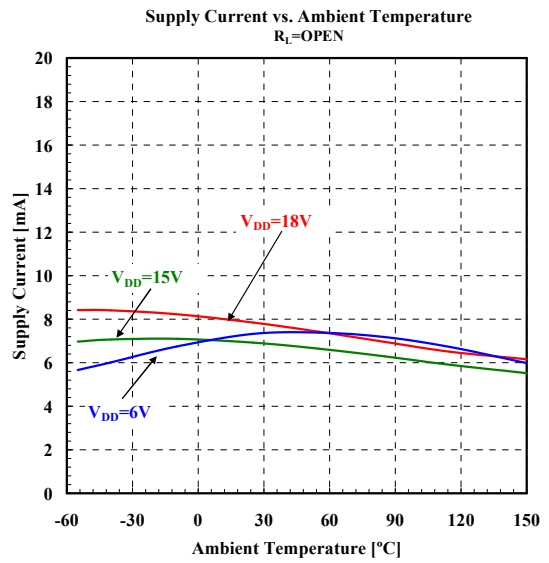
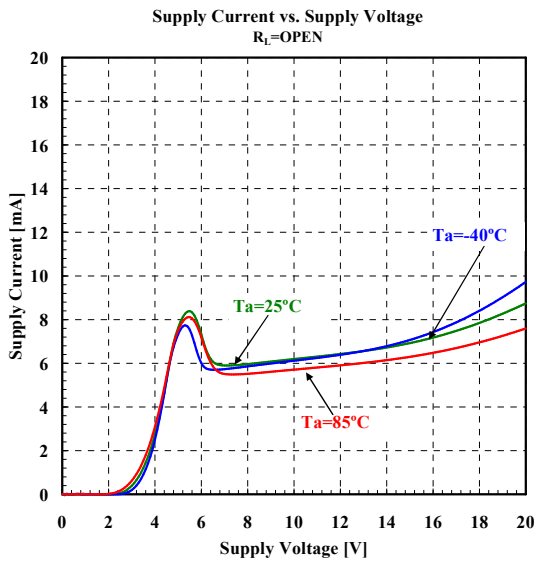
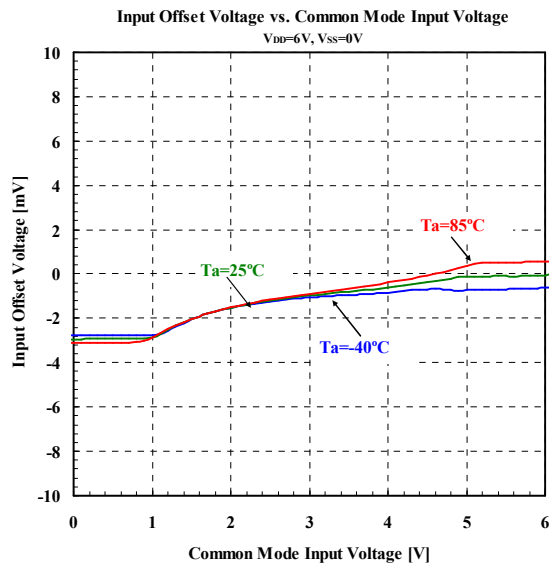
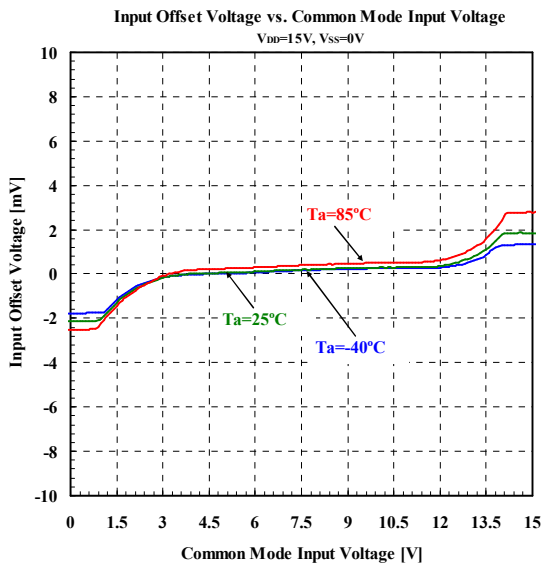
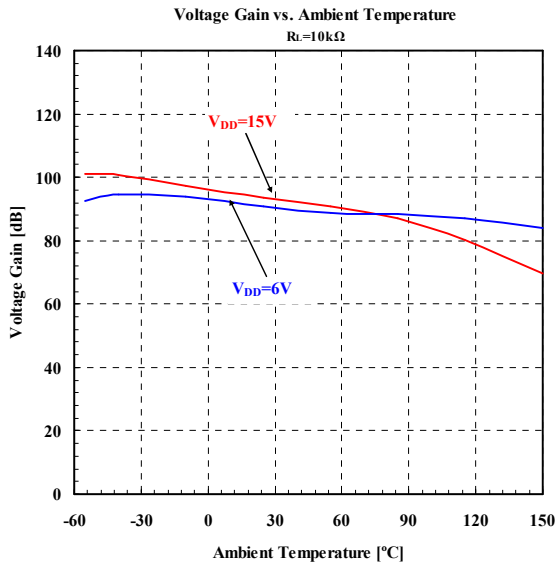
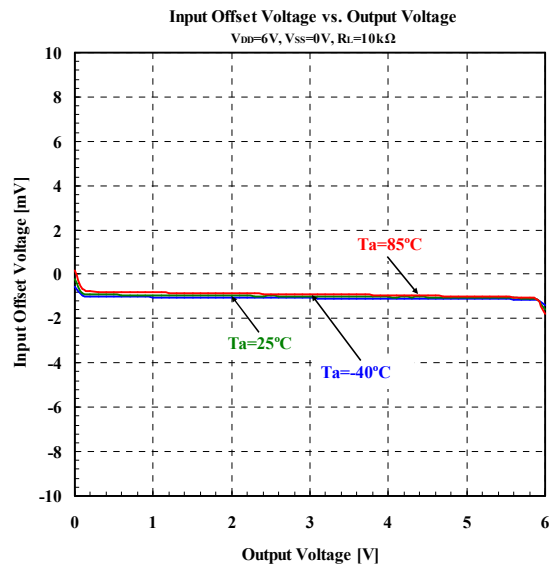
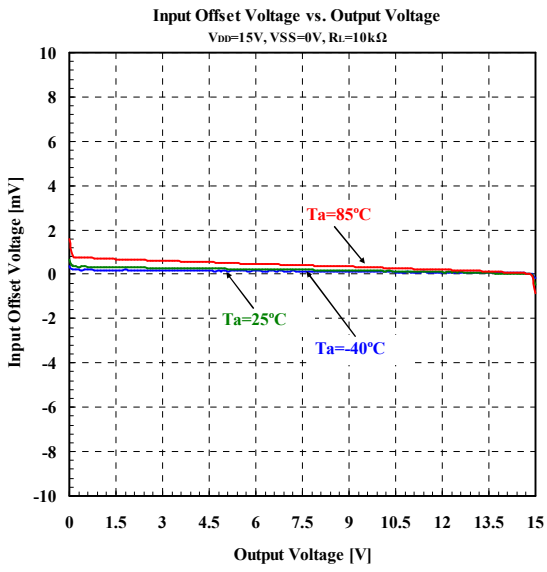
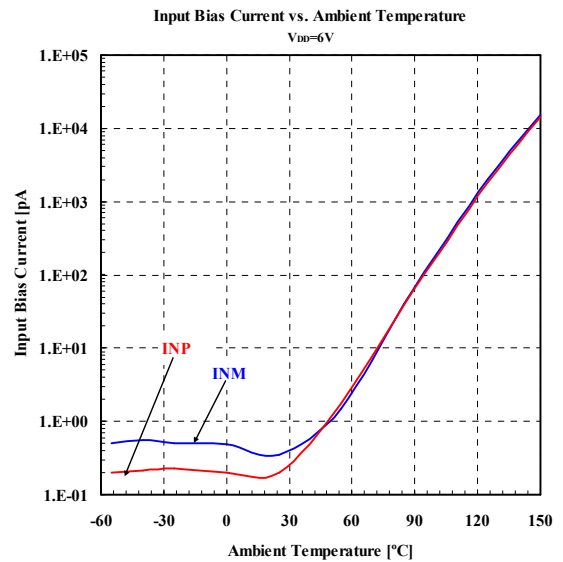
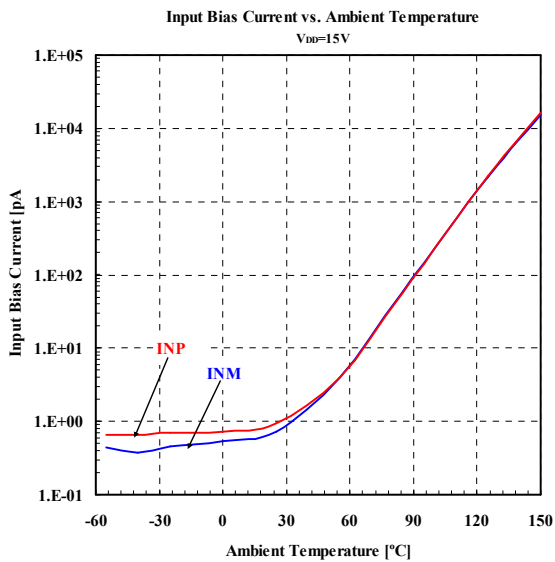
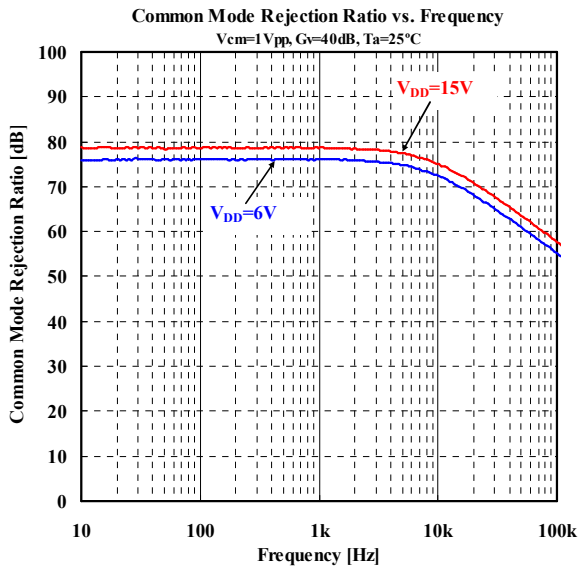
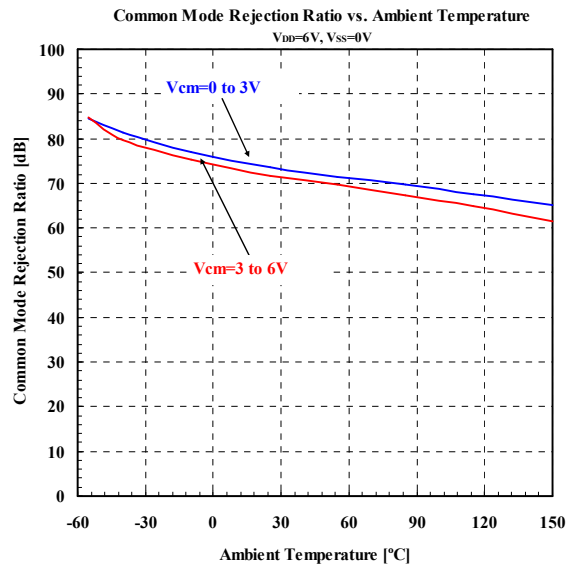
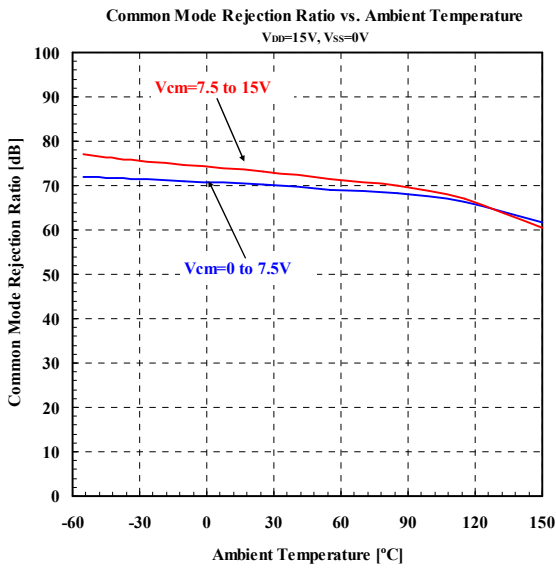


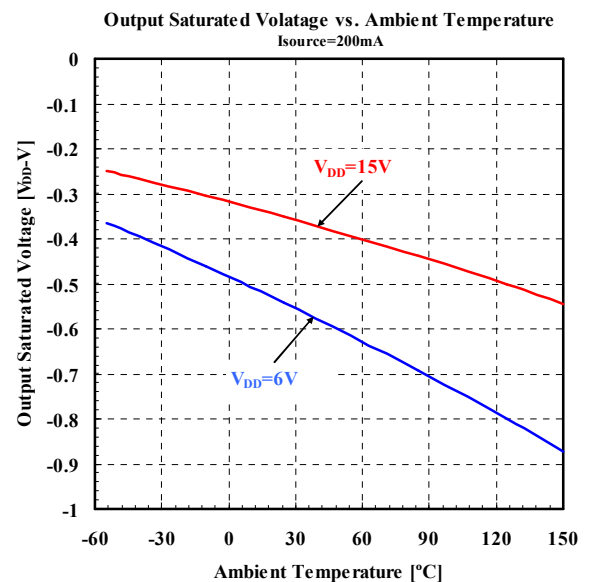
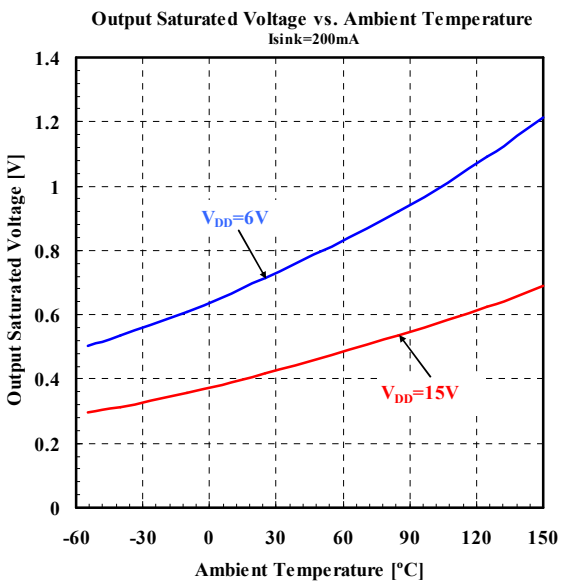
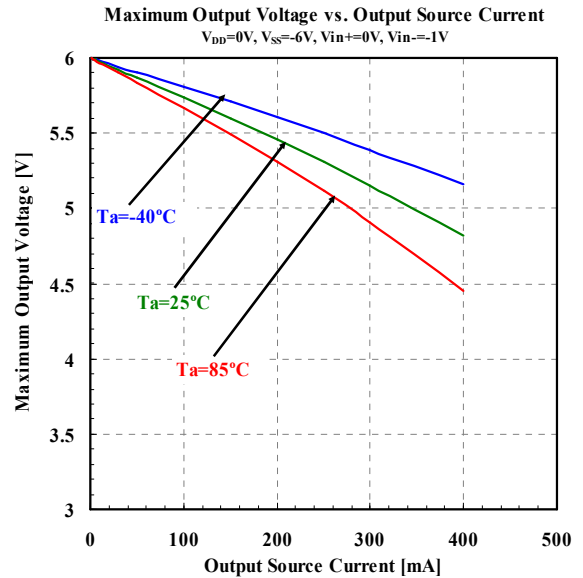
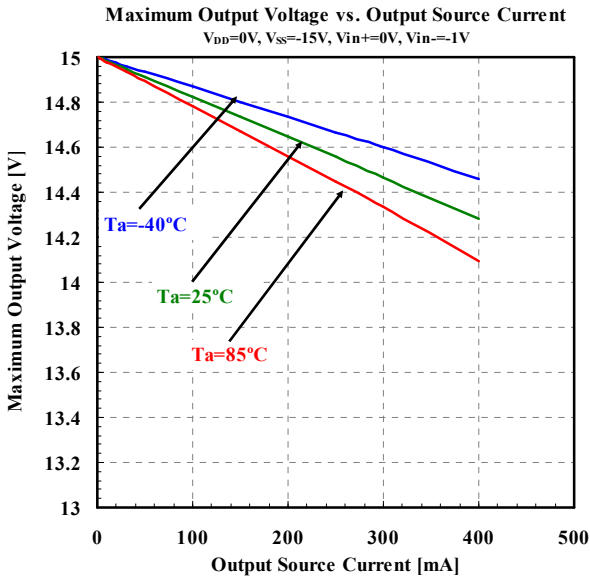
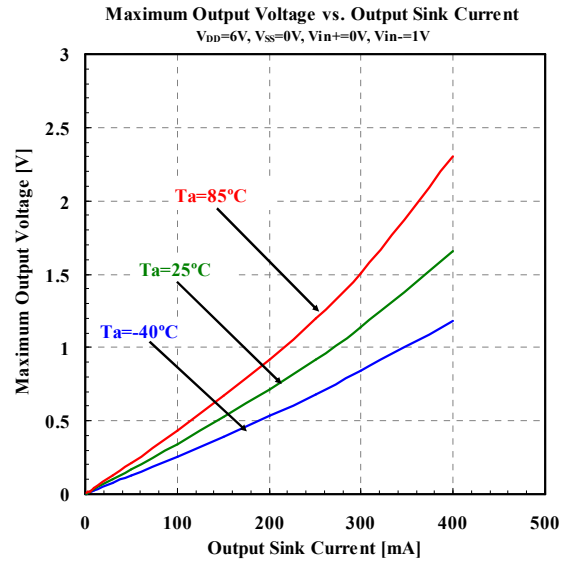
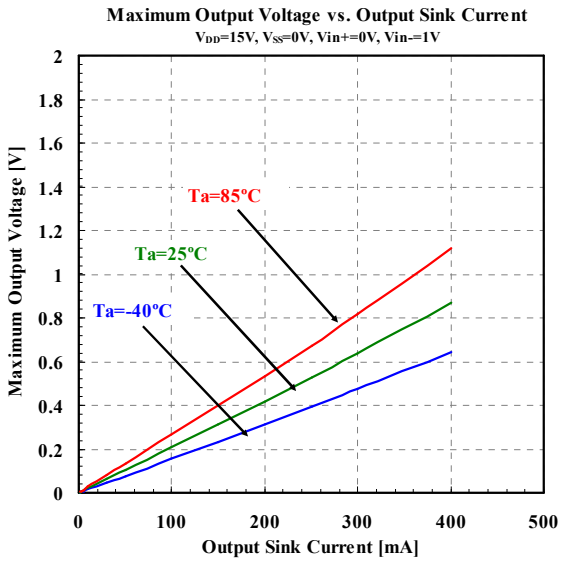
Fig1. Dependence of NJU77902 Power Dissipations on ambient temperature

## ■ TYPICAL CHARACTERISTICS

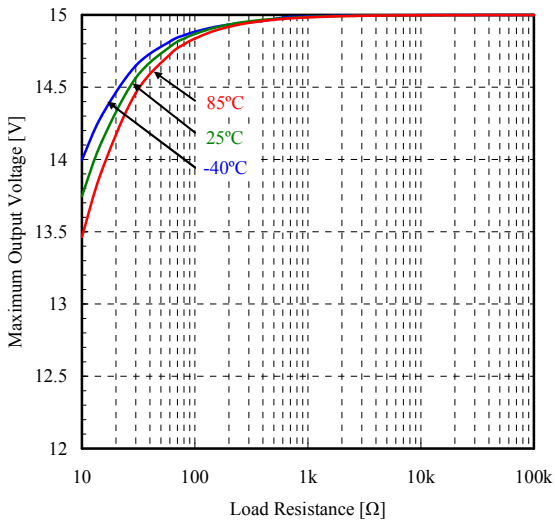




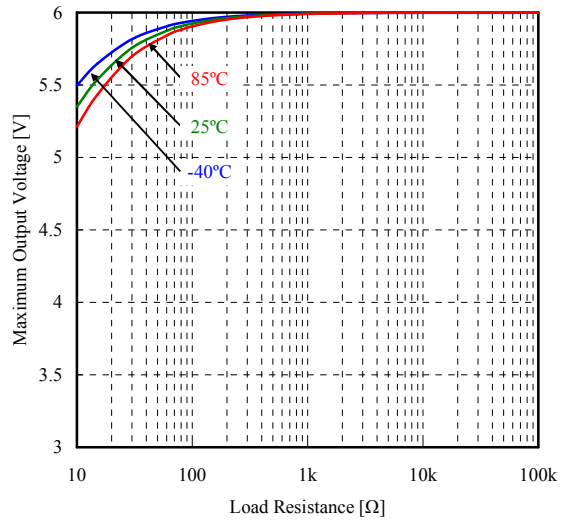




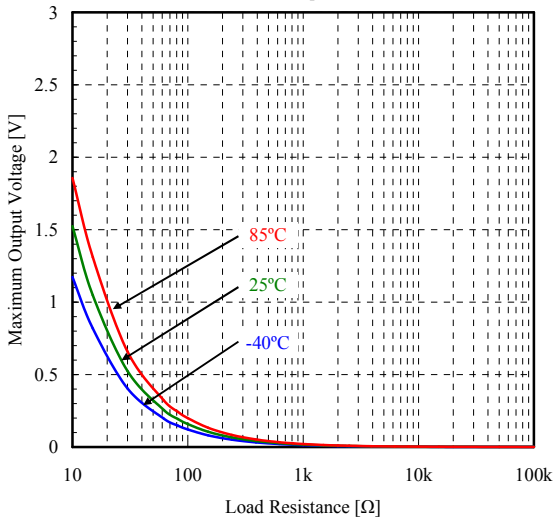
Maximum Output Voltage vs. Load Resistance  
 $V_{DD}=15V, G_v=open, R_L \text{ to } 7.5V$



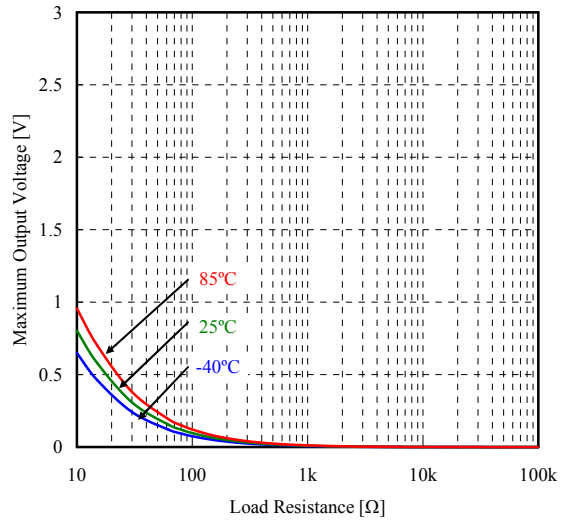
Maximum Output Voltage vs. Load Resistance  
 $V_{DD}=6V, G_v=open, R_L \text{ to } 3V$



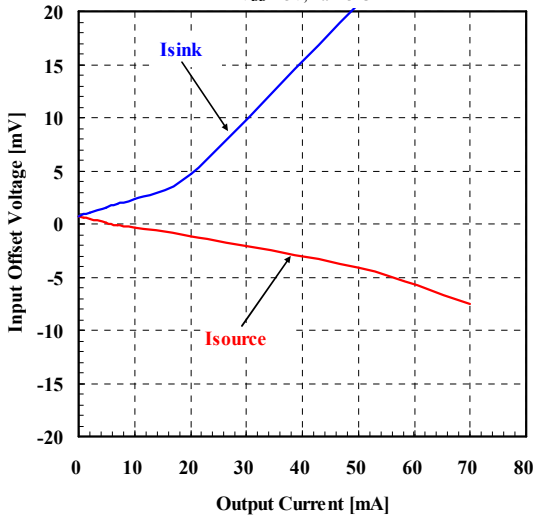
Maximum Output Voltage vs. Load Resistance  
 $V_{DD}=15V, G_v=open, R_L \text{ to } 7.5V$



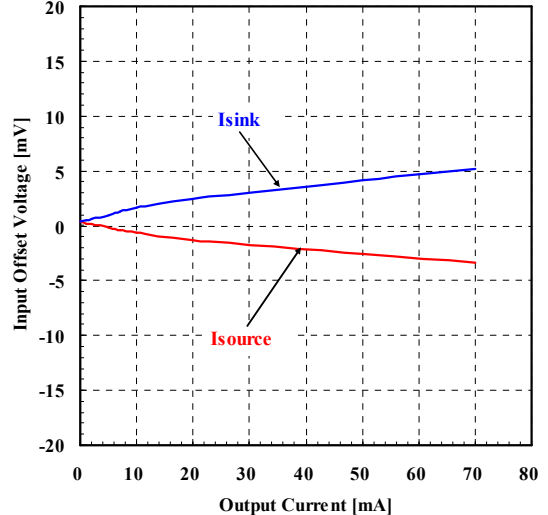
Maximum Output Voltage vs. Load Resistance  
 $V_{DD}=6V, G_v=open, R_L \text{ to } 3V$



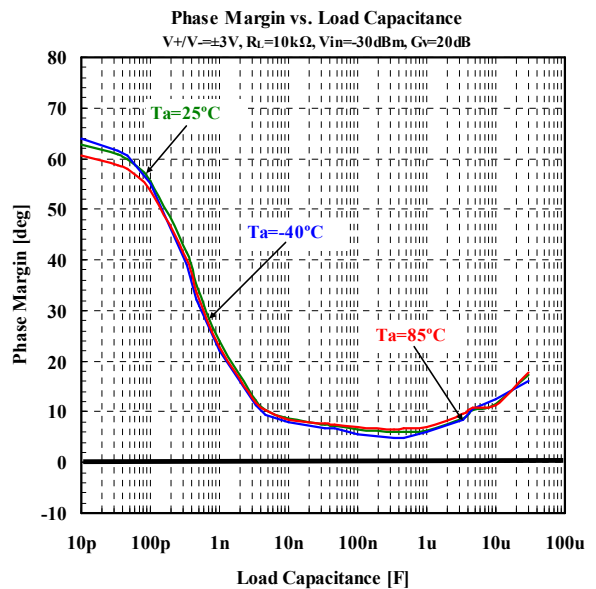
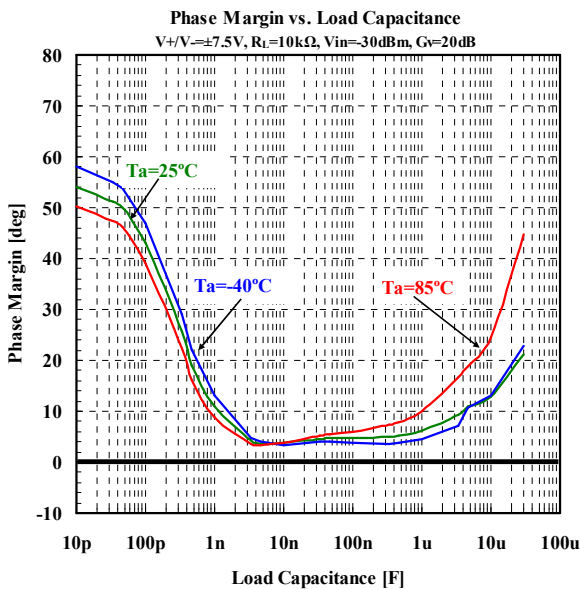
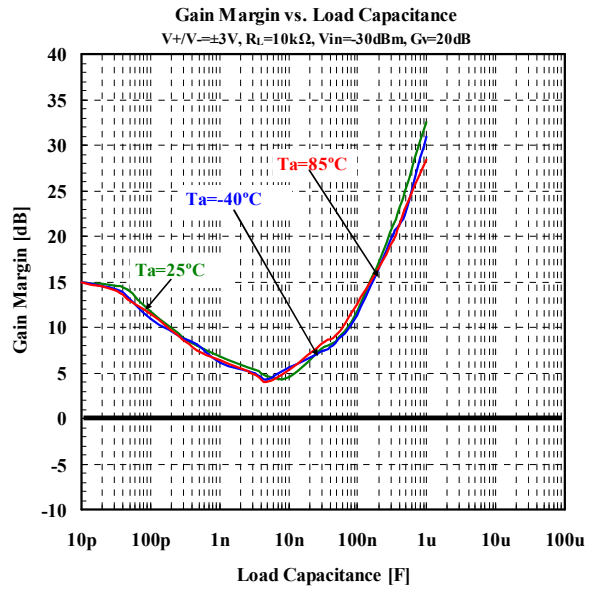
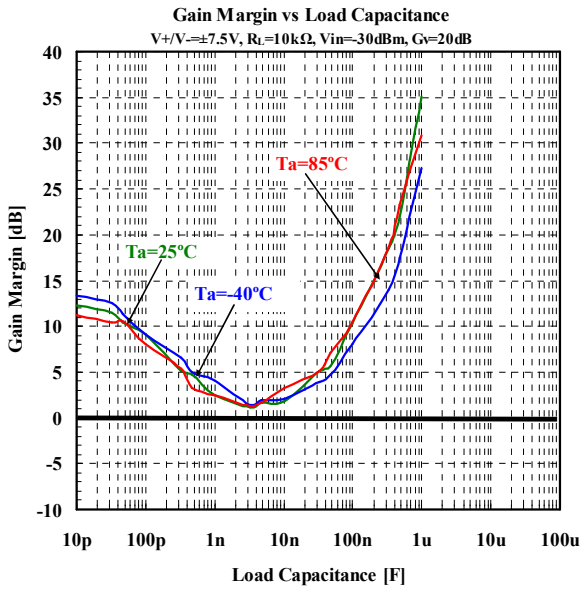
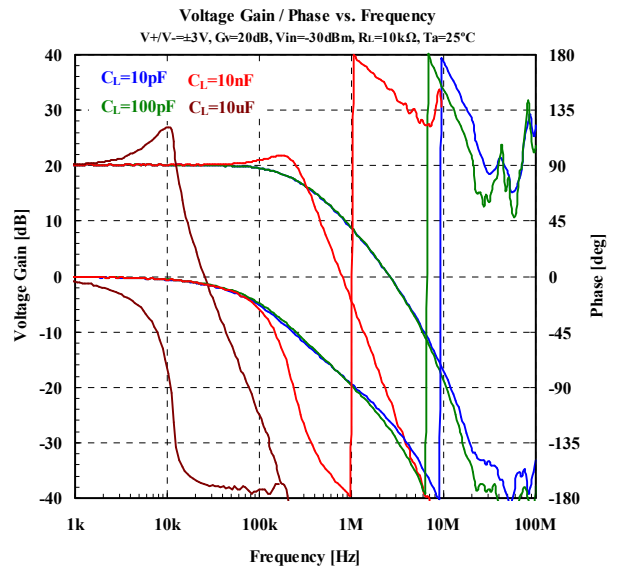
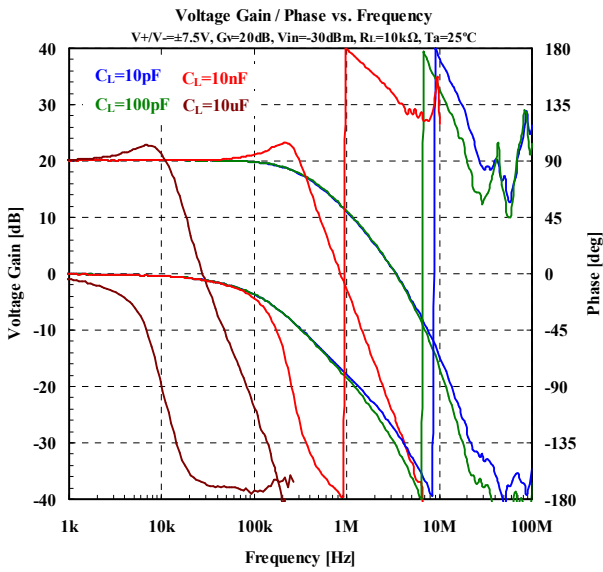
Input Offset Voltage vs. Output Current  
 $V_{DD}=15V, T_a=25^\circ C$

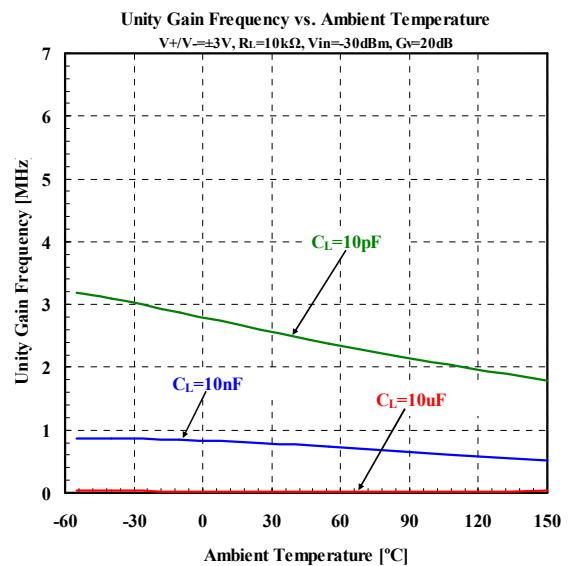
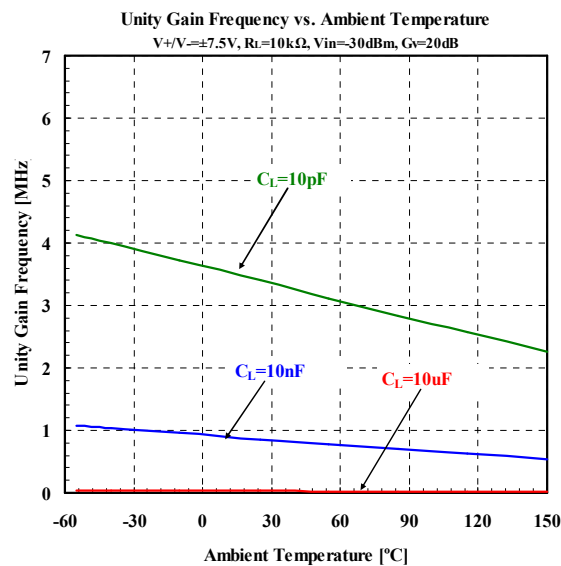
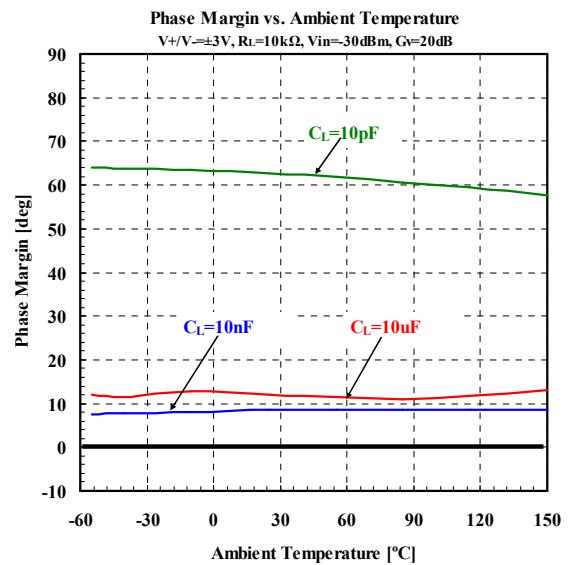
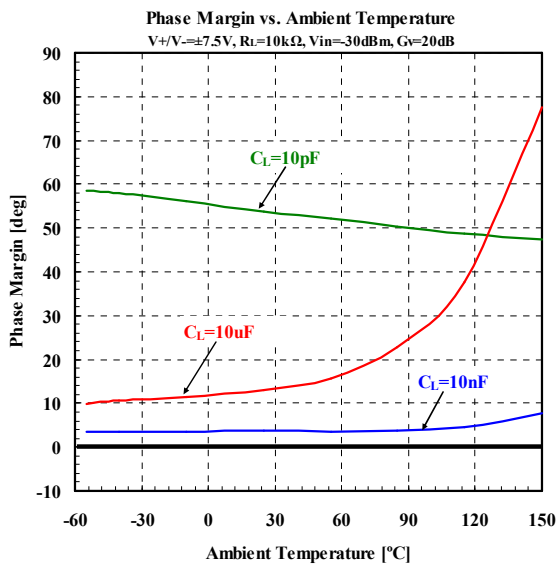
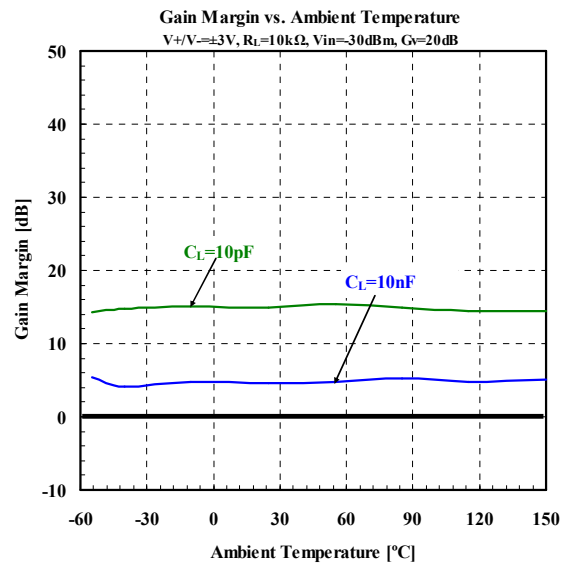
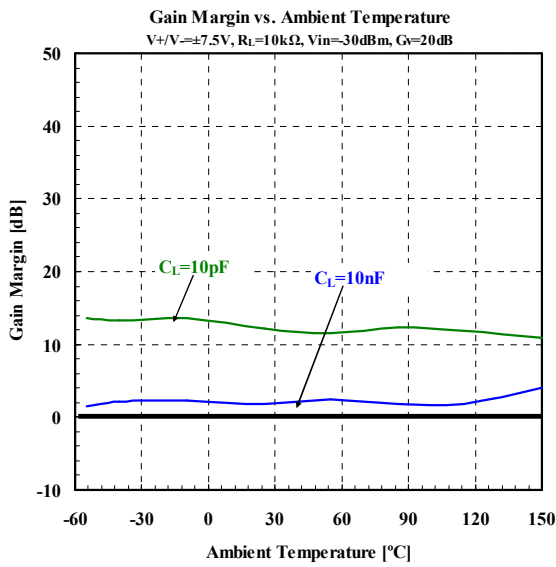


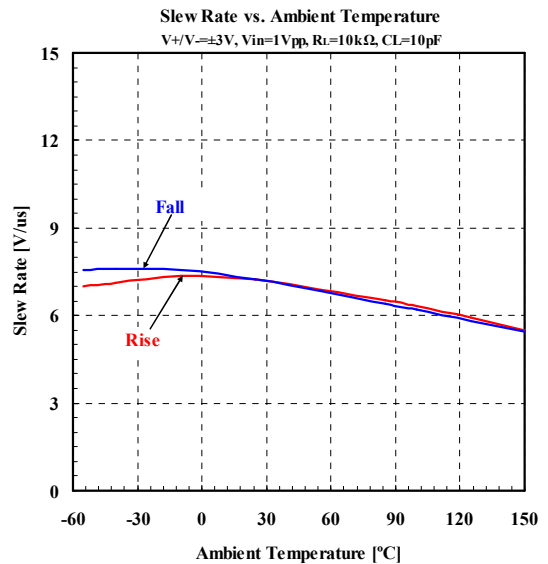
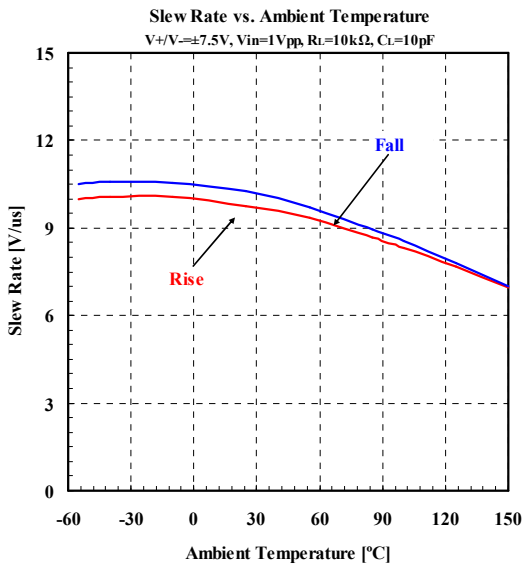
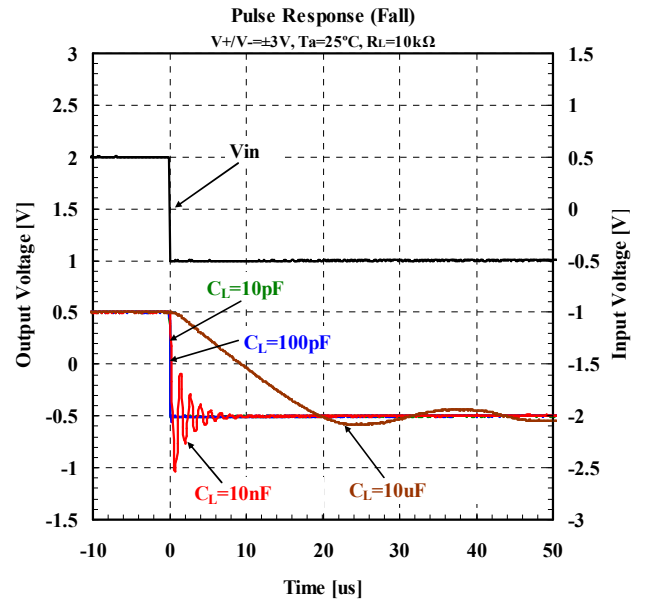
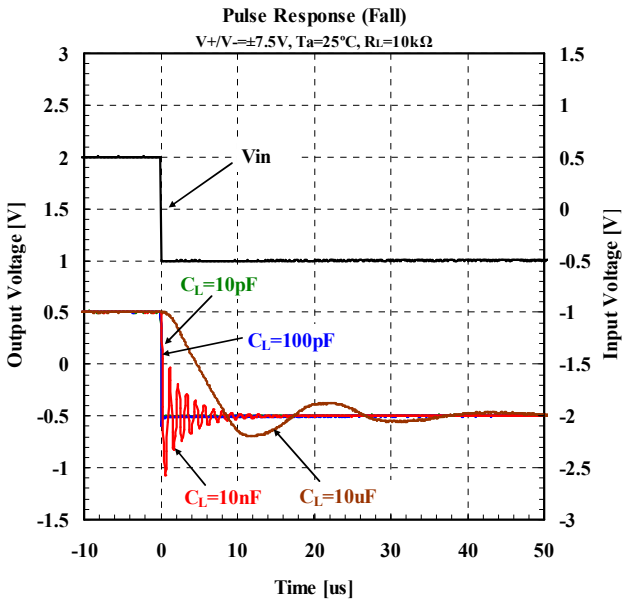
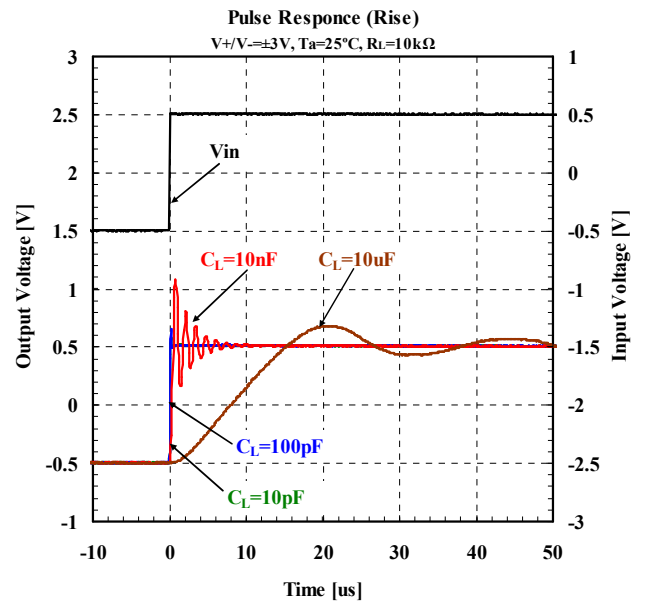
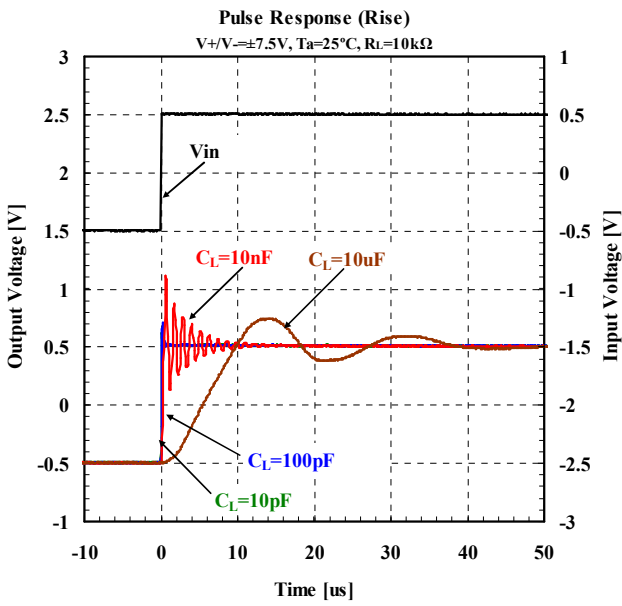
Input Offset Voltage vs. Output Current  
 $V_{DD}=6V, T_a=25^\circ C$

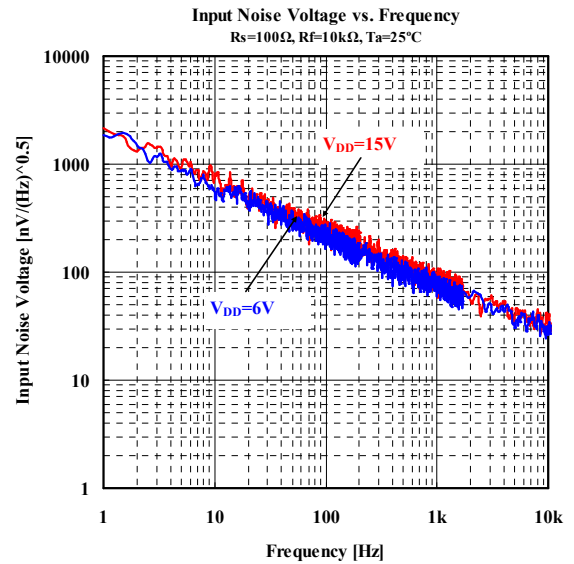
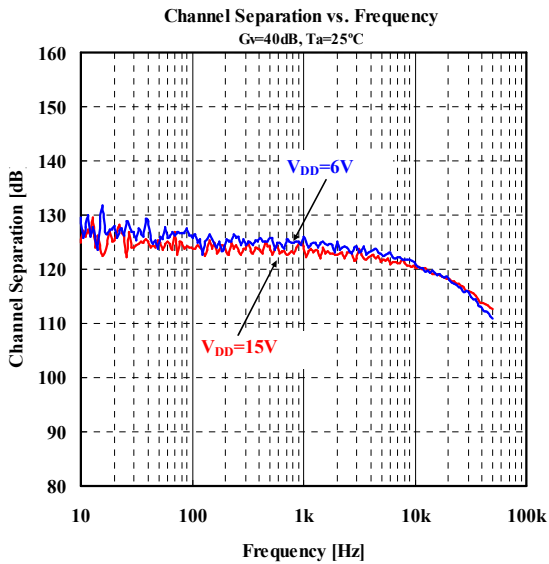
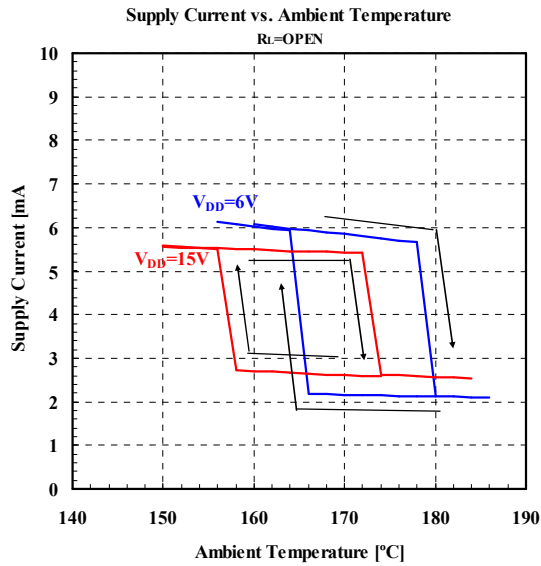
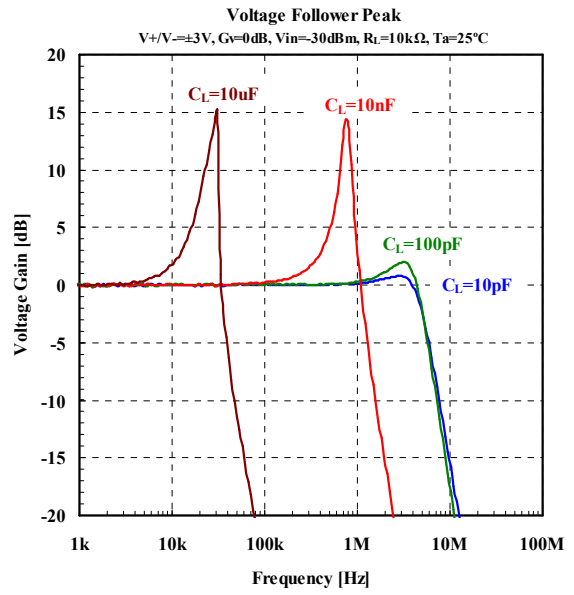
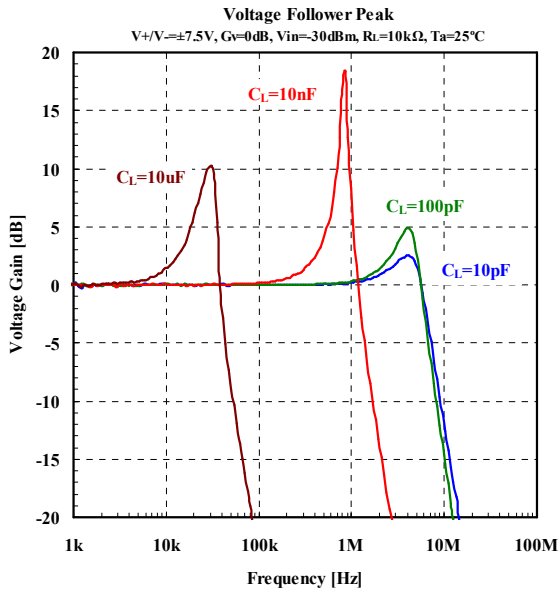


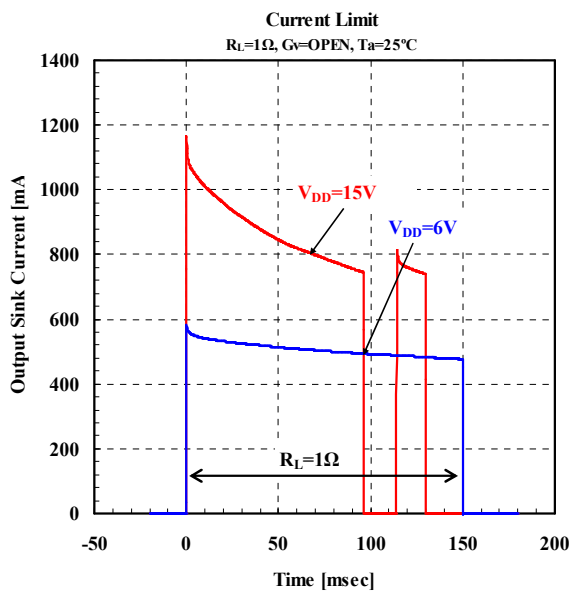
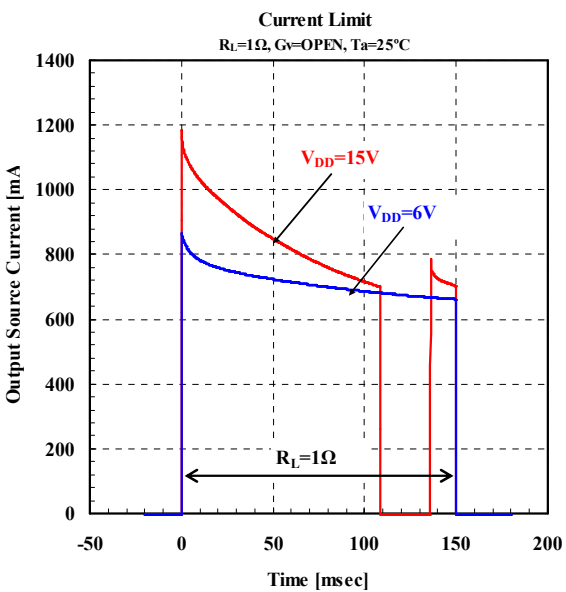
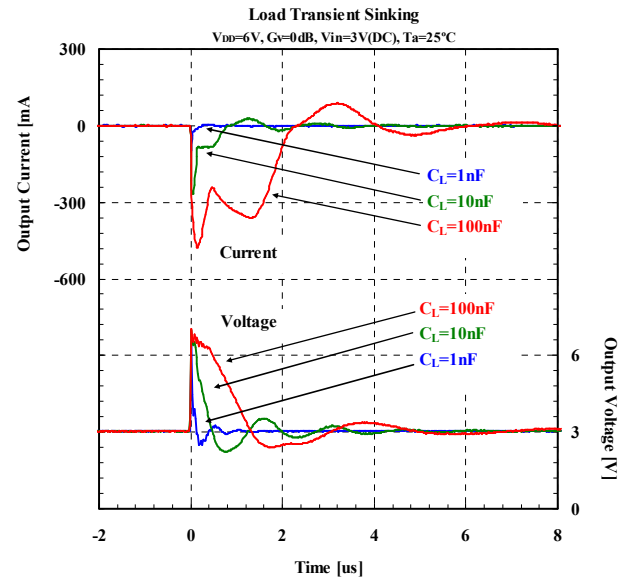
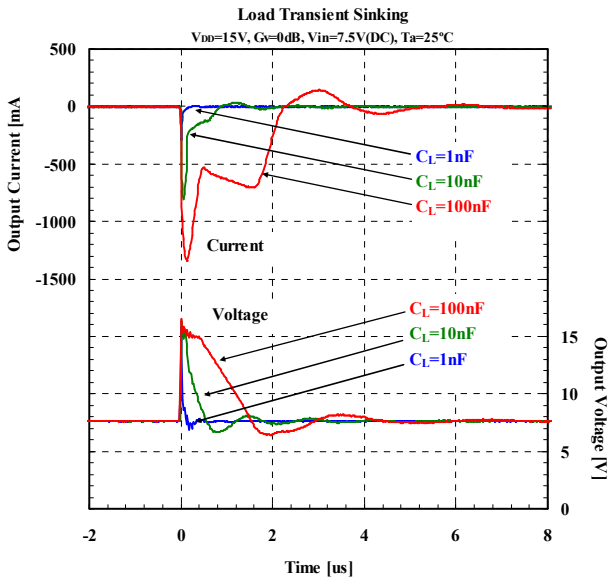
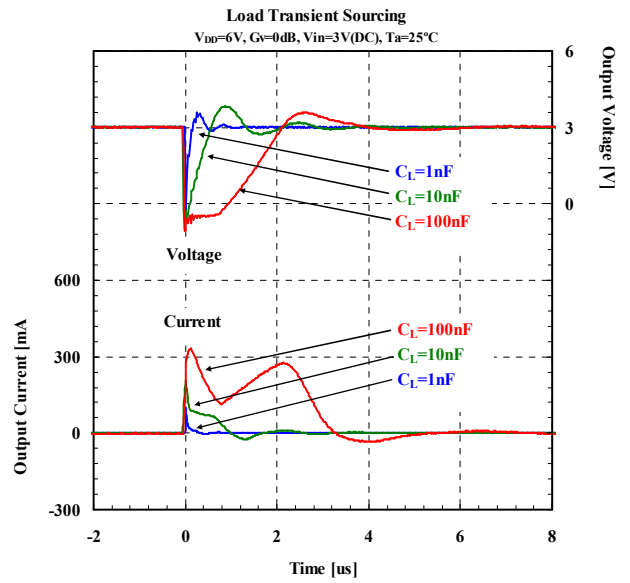
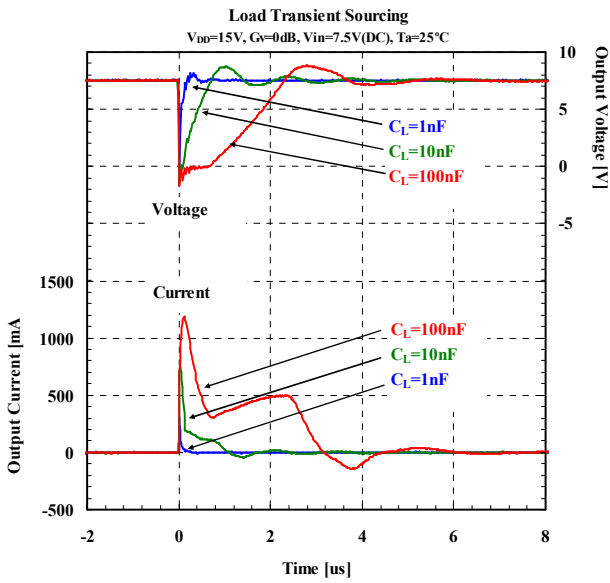


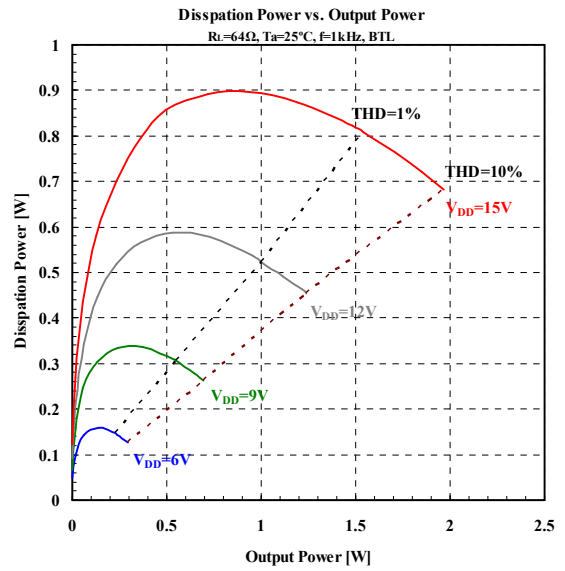
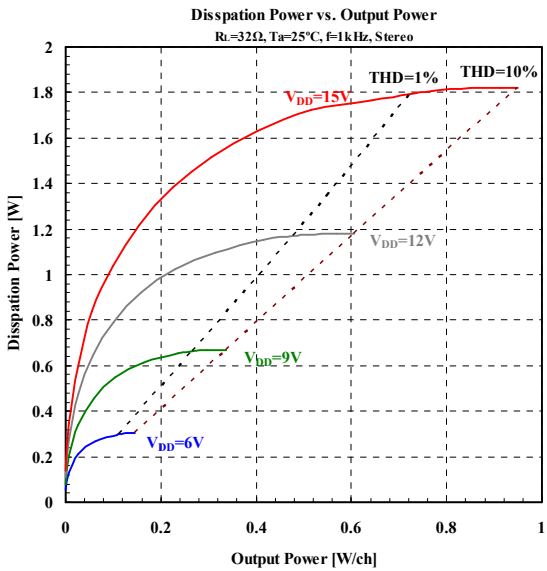
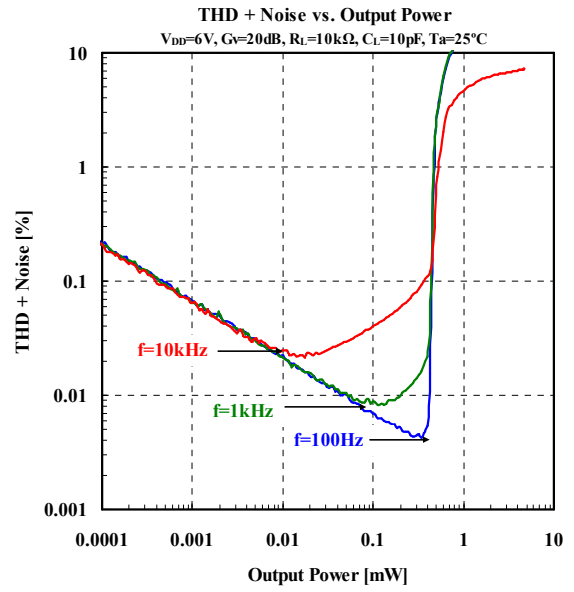
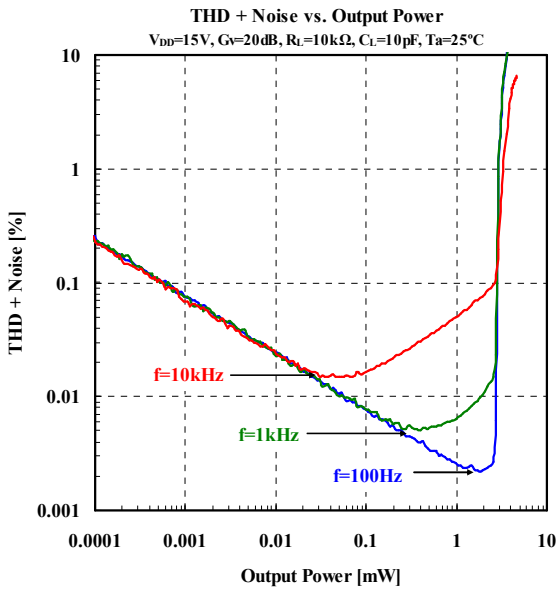












**[CAUTION]**

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